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	Approva	1 Sheet					
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	•	d in sending yo to us one copy		•			pproval.
7	型号 (Model	No.) :	<u> </u>	C-C01-2	2C		
,	发文日期(Is	sue Date): <u>2</u>	2019/12/09	承认日	期(Approve	ed Date):	
	Checkin	g signature o	f Amicc		Approval s	signature of o	customer
	Designer	Checker	Approver		Designer	Checker	Approver

江苏欧密格光电科技股份有限公司

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Mono-Color Type ■ Side view 1204 Package

A-SP110GHC-C01-2C



Features

- · 1204 package
- Side view LED
- Compatible with infrared and vapor phase reflow solder process.
- Wide viewing angle
- Pb-free
- · RoHS compliant

Description

The Amicc 110 package has high efficacy, high power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- · General lighting
- · Decorative and Entertainment Lighting
- Indicators
- Automotive Telecommunication
- Switch lights

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Brilliant Green	Water Clear



Absolute Maximum Ratings (T_{Soldering}=25℃)

Parameter	Symbol	Rating	Unit	
Forward Current	l _F	25	mA	
Peak Forward Current (Duty 1/10 @1ms)	I _{FP}	100	mA	
Power Dissipation	P _d	90	mW	
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}$ C	
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}$ C	
Soldering Temperature	T_{sol}	Reflow Soldering : 260 ℃ for 10 sec.		
Soldering reinperature		Hand Soldering : 350 ℃	for 3 sec.	

Note:

The products are sensitive to static electricity and must be carefully taken when handling products.

Electro-Optical Characteristics (T_{Soldering}=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	I_V	140		360	mcd	I _F =5mA
Peak Wavelength	λ_{p}		520		nm	I _F =5mA
Dominant Wavelength	λ_{d}	520		535	nm	I _F =5mA
Forward Voltage	V_{F}	2.4		3.1	V	I _F =5mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =5mA
Reverse Current	I _R			10	μΑ	V _R =5V

Note:

- 1. Tolerance of Luminous Intensity ±10%.
- 2. Tolerance of Dominant Wavelength ±1nm
- 3. Tolerance of Forward Voltage ±0.05V



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition	
AR2	140	180			
AS1	180	225	- mcd -	l =Εm Λ	
AS2	225	285		I _F =5mA	
AT1	285	360			

Note:

Tolerance of Luminous Intensity: ±10%.

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
A5	520	525		
A6	525	530	nm	I _F =5mA
A7	530	535	-	

Note:

Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage

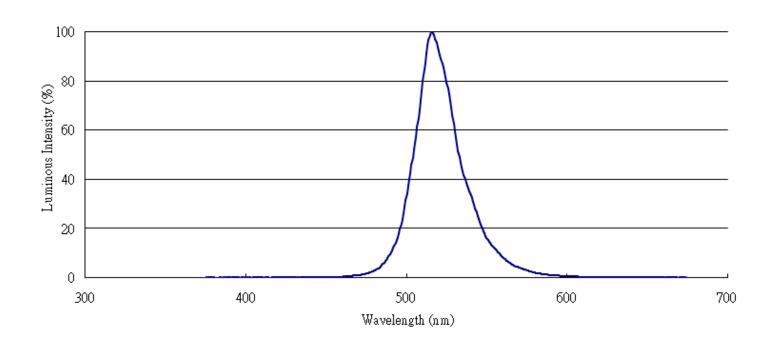
Bin Code	Min.	Max.	Unit	Condition
31	2.4	2.5		
32	2.5	2.6	-	
33	2.6	2.7	-	
34	2.7	2.8	V	I _F =5mA
35	2.8	2.9	-	
36	2.9	3.0	-	
37	3.0	3.1	-	

Note:

Tolerance of Forward Voltage: ±0.05V



Spectrum Distribution



Typical Electro-Optical Characteristics Curves

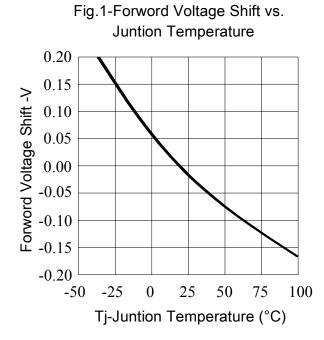
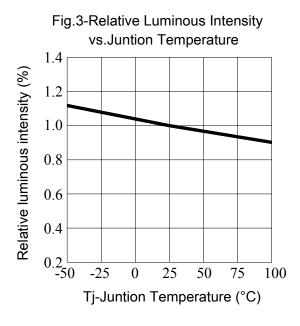
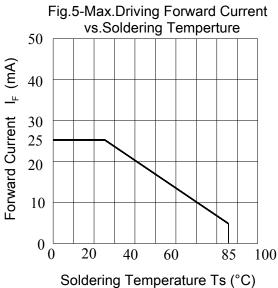


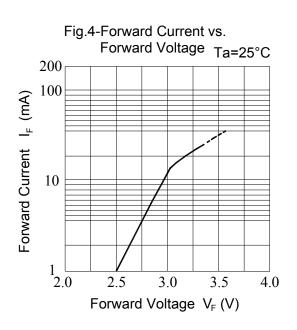
Fig.2-Relative Luminous Intensity vs. Forword Current Ts=25°C 1.6 Relative Luminous Intensity 1.4 (Normalized at 20mA) 1.0 0.8 0.6 0.4 0.2 0.0 30 0 5 10 15 25 20 Forward Current I_F (mA)

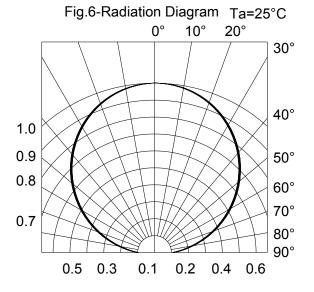


Typical Electro-Optical Characteristics Curve



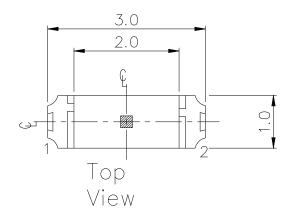




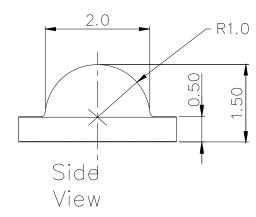


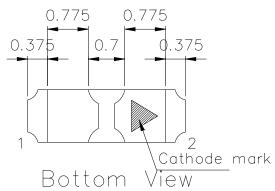


Package Dimension

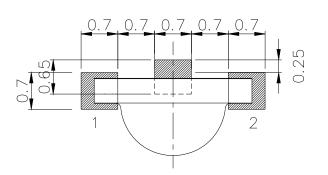








Recommended Solder Pad



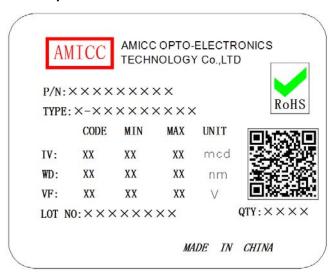
Note:

Tolerance unless mentioned is ± 0.1 mm, Unit = mm.



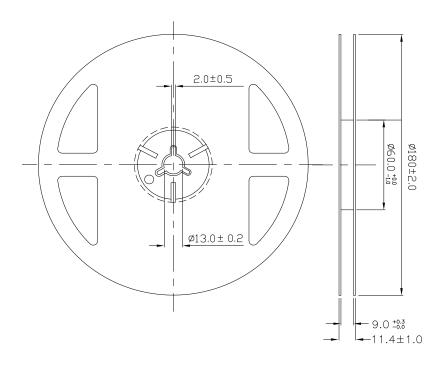
Moisture Resistant Packing Materials

Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- TYPE :Part NO.
- IV: Luminous Intensity Rank
- · WD: Dom. Wavelength Rank
- VF: Forward Voltage Rank
- LOT NO.: Lot Number
- · QTY: Packing Quantity

Reel Dimensions

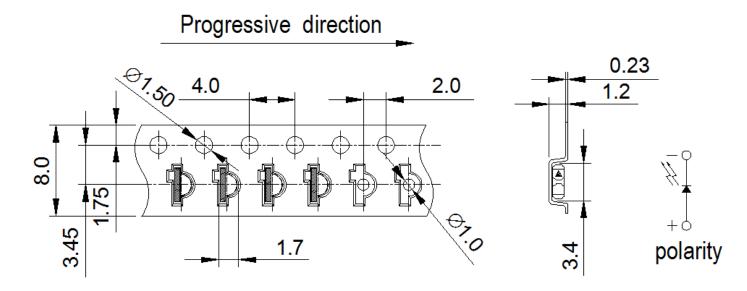


Note:

Tolerances unless mentioned ±0.1mm, Unit = mm.



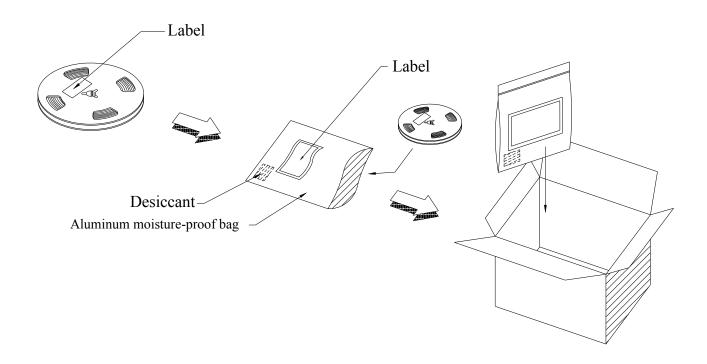
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note:

- 1. Tolerance unless mentioned is ± 0.1 mm, Unit = mm.
- 2. Minimum packing amount is 1000 pcs per reel.

Moisture Resistant Packing Process





Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity	Ta=85℃,85%RH	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
6	High Temperature Storage	Ta=100℃	1000 Hrs.	22 PCS.	0/1
7	DC Operation Life	Ta=25℃, I _F = 5 mA	1000 Hrs.	22 PCS.	0/1



Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

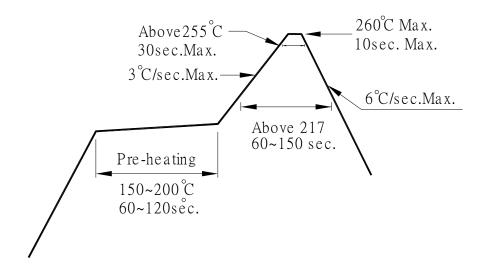
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 years 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

